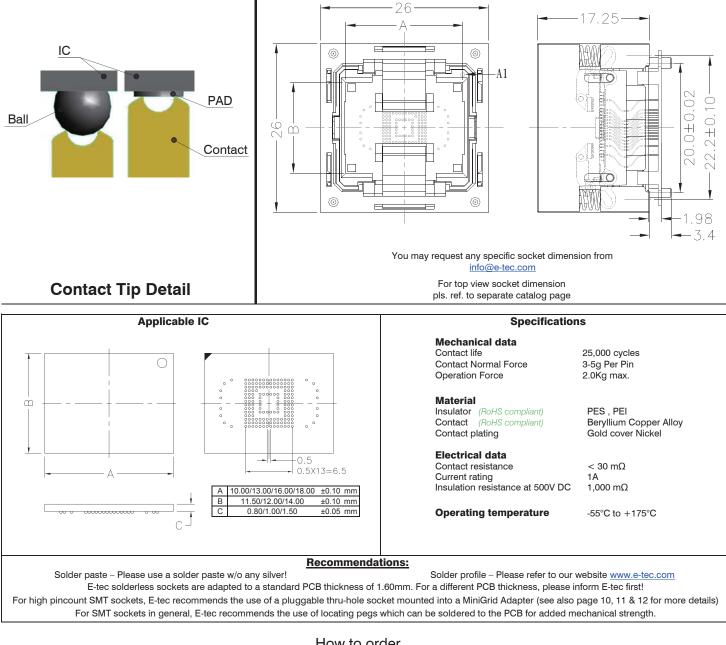


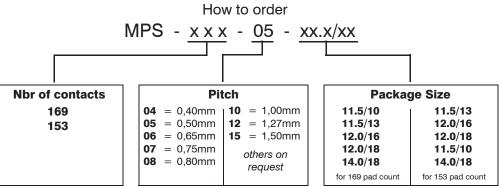


Open Top Style. Accommodates Chip Scale Package with 0.5mm pitch. Compact size and low actuation force. 4-point pinch design for enhanced electrical contact. Field exchangeable package location plate. "U" contact supports any pad or solder ball shape and composition.

## Please note, we will always request the chip data to ensure we offer a compatible socket.











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